

# ISL9V3036D3S / ISL9V3036S3S / ISL9V3036P3

## EcoSPARK™ 300mJ, 360V, N-Channel Ignition IGBT

### General Description

The ISL9V3036D3S, ISL9V3036S3S, and ISL9V3036P3 are the next generation IGBTs that offer outstanding SCIS capability in the space saving D-Pak (TO-252), as well as the industry standard D<sup>2</sup>-Pak (TO-263) and TO-220 plastic packages. These devices are intended for use in automotive ignition circuits, specifically as a coil drivers. Internal diodes provide voltage clamping without the need for external components.

**EcoSPARK™** devices can be custom made to specific clamp voltages. Contact your nearest Fairchild sales office for more information.

Formerly Developmental Type 49442

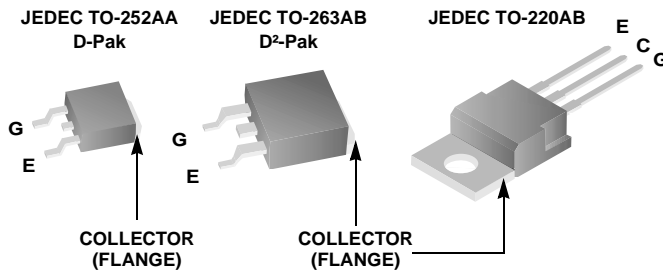
### Applications

- Automotive Ignition Coil Driver Circuits
- Coil- On Plug Applications

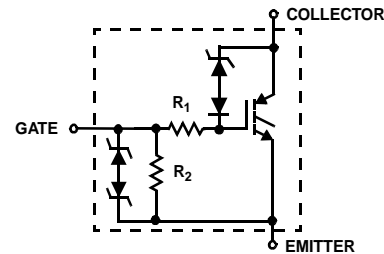
### Features

- Industry Standard D<sup>2</sup>-Pak package
- SCIS Energy = 300mJ at T<sub>J</sub> = 25°C
- Logic Level Gate Drive

### Package



### Symbol



### Device Maximum Ratings T<sub>J</sub> = 25°C unless otherwise noted

Symbol	Parameter	Ratings	Units
BV <sub>CER</sub>	Collector to Emitter Breakdown Voltage (I <sub>C</sub> = 1 mA)	360	V
BV <sub>ECS</sub>	Emitter to Collector Voltage - Reverse Battery Condition (I <sub>C</sub> = 10 mA)	24	V
E <sub>SCIS25</sub>	T <sub>J</sub> = 25°C, I <sub>SCIS</sub> = 14.2A, L = 3.0 mHy	300	mJ
E <sub>SCIS150</sub>	T <sub>J</sub> = 150°C, I <sub>SCIS</sub> = 10.6A, L = 3.0 mHy	170	mJ
I <sub>C25</sub>	Collector Current Continuous, At T <sub>C</sub> = 25°C, See Fig 9	21	A
I <sub>C110</sub>	Collector Current Continuous, At T <sub>C</sub> = 110°C, See Fig 9	17	A
V <sub>GEM</sub>	Gate to Emitter Voltage Continuous	±10	V
P <sub>D</sub>	Power Dissipation Total T <sub>C</sub> = 25°C	150	W
	Power Dissipation Derating T <sub>C</sub> > 25°C	1.0	W/°C
T <sub>J</sub>	Operating Junction Temperature Range	-40 to 175	°C
T <sub>STG</sub>	Storage Junction Temperature Range	-40 to 175	°C
T <sub>L</sub>	Max Lead Temp for Soldering (Leads at 1.6mm from Case for 10s)	300	°C
T <sub>pkg</sub>	Max Lead Temp for Soldering (Package Body for 10s)	260	°C
ESD	Electrostatic Discharge Voltage at 100pF, 1500Ω	4	kV

## Package Marking and Ordering Information

Device Marking	Device	Package	Tape Width	Quantity
V3036D	ISL9V3036D3S	TO-252AA	16mm	2500
V3036S	ISL9V3036S3S	TO-263AB	24mm	800
V3036P	ISL9V3036P3	TO-220AA	-	-

## Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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### Off State Characteristics

$BV_{CER}$	Collector to Emitter Breakdown Voltage	$I_C = 2\text{mA}$ , $V_{GE} = 0$ , $R_G = 1\text{K}\Omega$ , See Fig. 15 $T_J = -40$ to $150^\circ\text{C}$	330	360	390	V	
$BV_{CES}$	Collector to Emitter Breakdown Voltage	$I_C = 10\text{mA}$ , $V_{GE} = 0$ , $R_G = 0$ , See Fig. 15 $T_J = -40$ to $150^\circ\text{C}$	350	380	410	V	
$BV_{ECS}$	Emitter to Collector Breakdown Voltage	$I_C = -75\text{mA}$ , $V_{GE} = 0\text{V}$ , $T_C = 25^\circ\text{C}$	30	-	-	V	
$BV_{GES}$	Gate to Emitter Breakdown Voltage	$I_{GES} = \pm 2\text{mA}$	$\pm 12$	$\pm 14$	-	V	
$I_{CER}$	Collector to Emitter Leakage Current	$V_{CER} = 250\text{V}$ , $R_G = 1\text{K}\Omega$ , See Fig. 11	$T_C = 25^\circ\text{C}$	-	-	25	$\mu\text{A}$
			$T_C = 150^\circ\text{C}$	-	-	1	$\text{mA}$
$I_{ECS}$	Emitter to Collector Leakage Current	$V_{EC} = 24\text{V}$ , See Fig. 11	$T_C = 25^\circ\text{C}$	-	-	1	$\text{mA}$
			$T_C = 150^\circ\text{C}$	-	-	40	$\text{mA}$
$R_1$	Series Gate Resistance		-	70	-	$\Omega$	
$R_2$	Gate to Emitter Resistance		10K	-	26K	$\Omega$	

### On State Characteristics

$V_{CE(SAT)}$	Collector to Emitter Saturation Voltage	$I_C = 6\text{A}$ , $V_{GE} = 4\text{V}$	$T_C = 25^\circ\text{C}$ , See Fig. 3	-	1.25	1.60	V
$V_{CE(SAT)}$	Collector to Emitter Saturation Voltage	$I_C = 10\text{A}$ , $V_{GE} = 4.5\text{V}$	$T_C = 150^\circ\text{C}$ , See Fig. 4	-	1.58	1.80	V
$V_{CE(SAT)}$	Collector to Emitter Saturation Voltage	$I_C = 15\text{A}$ , $V_{GE} = 4.5\text{V}$	$T_C = 150^\circ\text{C}$	-	1.90	2.20	V

### Dynamic Characteristics

$Q_{G(ON)}$	Gate Charge	$I_C = 10\text{A}$ , $V_{CE} = 12\text{V}$ , $V_{GE} = 5\text{V}$ , See Fig. 14	-	17	-	$\text{nC}$	
$V_{GE(TH)}$	Gate to Emitter Threshold Voltage	$I_C = 1.0\text{mA}$ , $V_{CE} = V_{GE}$ , See Fig. 10	$T_C = 25^\circ\text{C}$	1.3	-	2.2	V
			$T_C = 150^\circ\text{C}$	0.75	-	1.8	V
$V_{GEP}$	Gate to Emitter Plateau Voltage	$I_C = 10\text{A}$ , $V_{CE} = 12\text{V}$	-	3.0	-	V	

### Switching Characteristics

$t_{d(ON)R}$	Current Turn-On Delay Time-Resistive	$V_{CE} = 14\text{V}$ , $R_L = 1\Omega$ , $V_{GE} = 5\text{V}$ , $R_G = 1\text{K}\Omega$ , $T_J = 25^\circ\text{C}$ , See Fig. 12	-	0.7	4	$\mu\text{s}$
$t_{rR}$	Current Rise Time-Resistive		-	2.1	7	$\mu\text{s}$
$t_{d(OFF)L}$	Current Turn-Off Delay Time-Inductive	$V_{CE} = 300\text{V}$ , $R_L = 500\mu\text{H}$ , $V_{GE} = 5\text{V}$ , $R_G = 1\text{K}\Omega$ , $T_J = 25^\circ\text{C}$ , See Fig. 12	-	4.8	15	$\mu\text{s}$
$t_{fL}$	Current Fall Time-Inductive		-	2.8	15	$\mu\text{s}$
SCIS	Self Clamped Inductive Switching	$T_J = 25^\circ\text{C}$ , $L = 3.0\text{mH}$ , $R_G = 1\text{K}\Omega$ , $V_{GE} = 5\text{V}$ , See Fig. 1 & 2	-	-	300	$\text{mJ}$

### Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance Junction-Case	TO-252, TO-263, TO-220	-	-	1.0	$^\circ\text{C/W}$
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Typical Performance Curves (Continued)

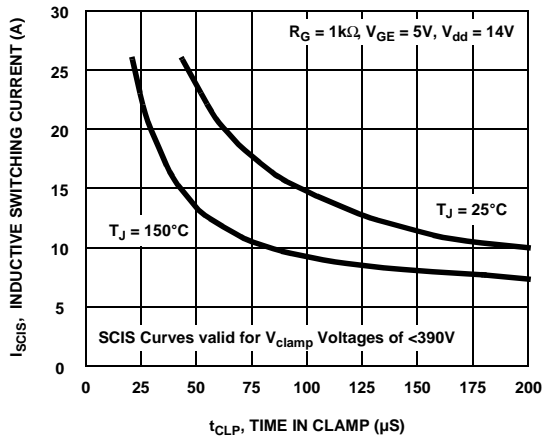


Figure 1. Self Clamped Inductive Switching Current vs Time in Clamp

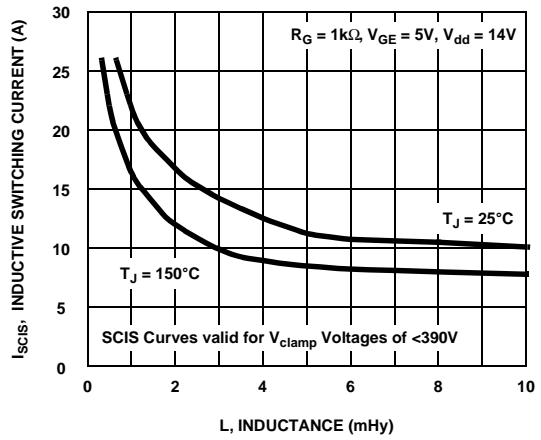


Figure 2. Self Clamped Inductive Switching Current vs Inductance

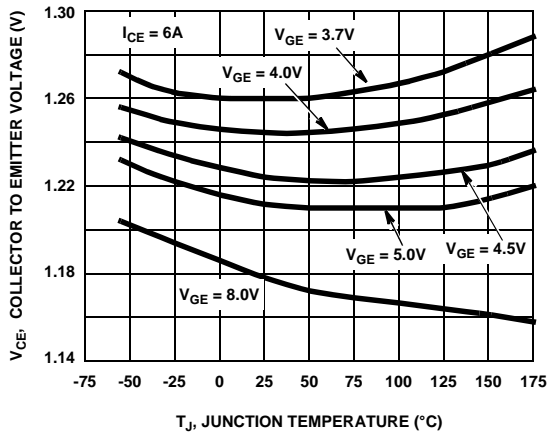


Figure 3. Collector to Emitter On-State Voltage vs Junction Temperature

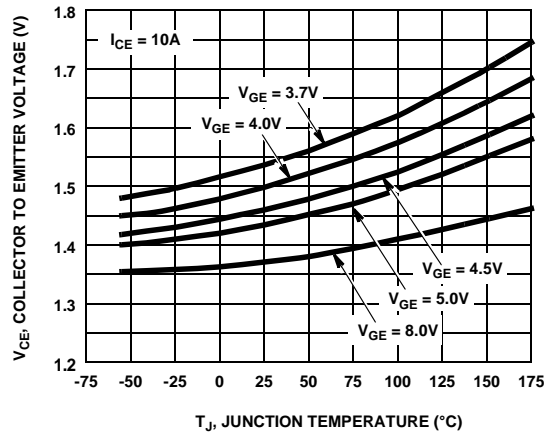


Figure 4. Collector to Emitter On-State Voltage vs Junction Temperature

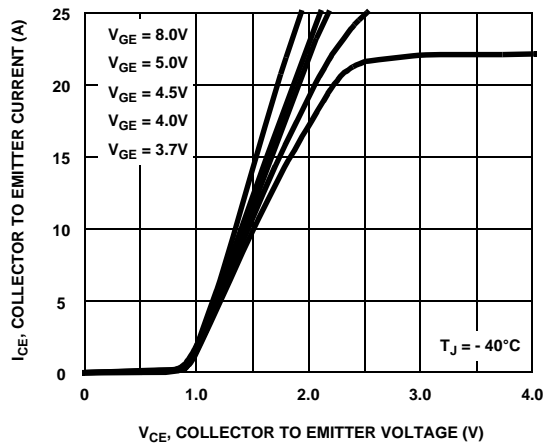


Figure 5. Collector to Emitter On-State Voltage vs Collector Current

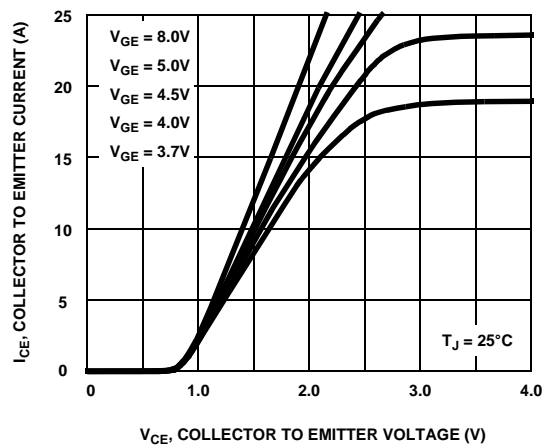


Figure 6. Collector to Emitter On-State Voltage vs Collector Current

Typical Performance Curves (Continued)

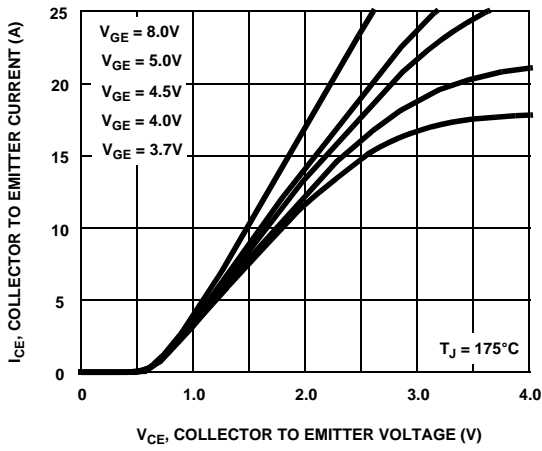


Figure 7. Collector to Emitter On-State Voltage vs Collector Current

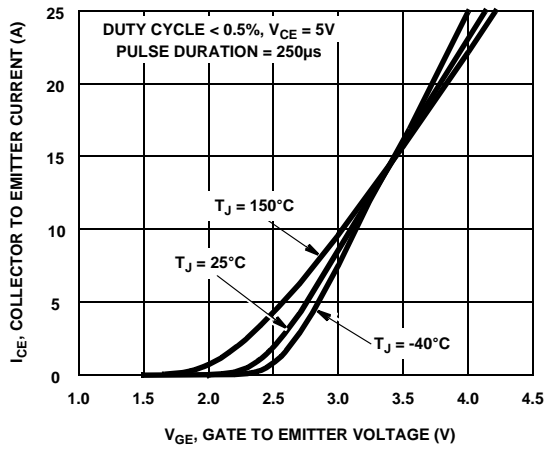


Figure 8. Transfer Characteristics

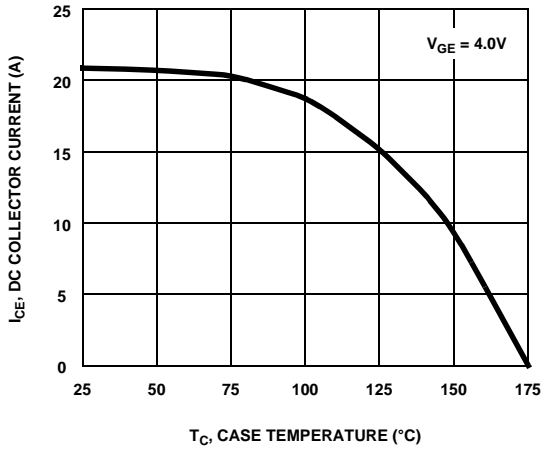


Figure 9. DC Collector Current vs Case Temperature

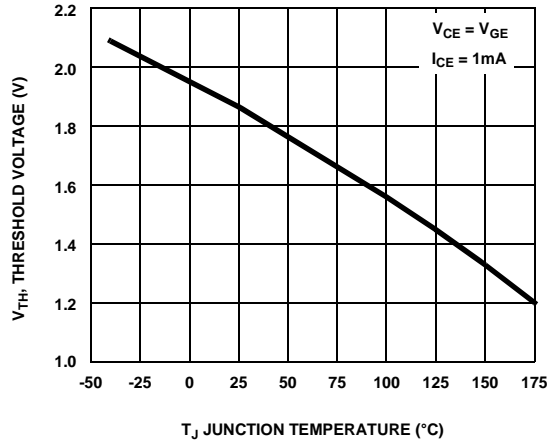


Figure 10. Threshold Voltage vs Junction Temperature

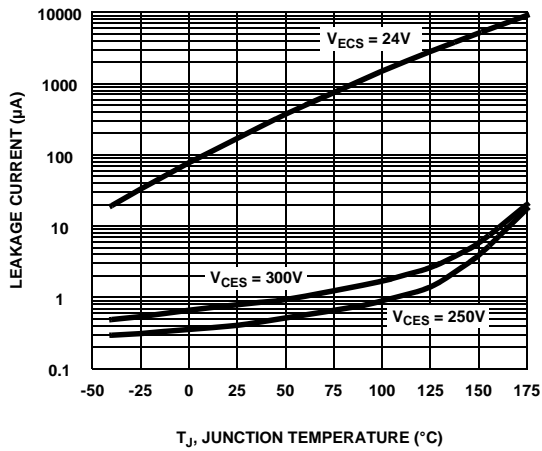


Figure 11. Leakage Current vs Junction Temperature

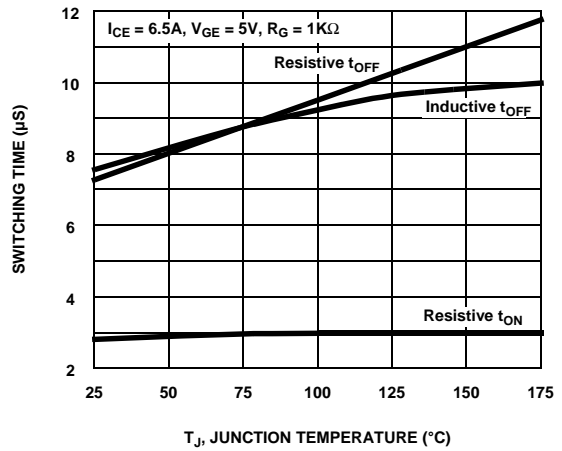


Figure 12. Switching Time vs Junction Temperature

Typical Performance Curves (Continued)

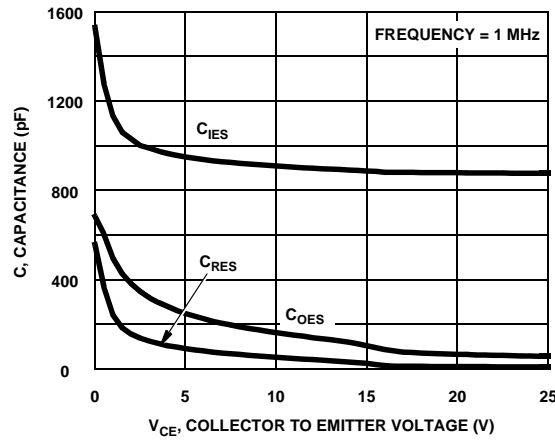


Figure 13. Capacitance vs Collector to Emitter Voltage

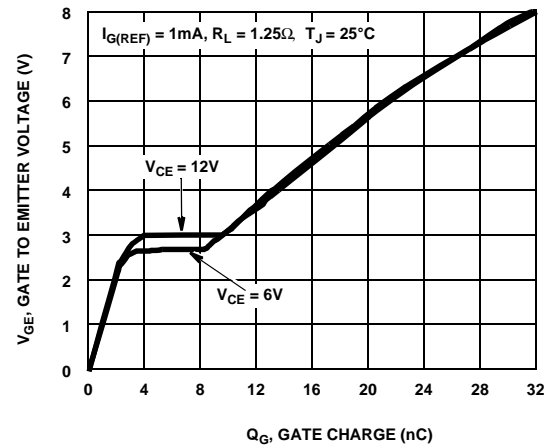


Figure 14. Gate Charge

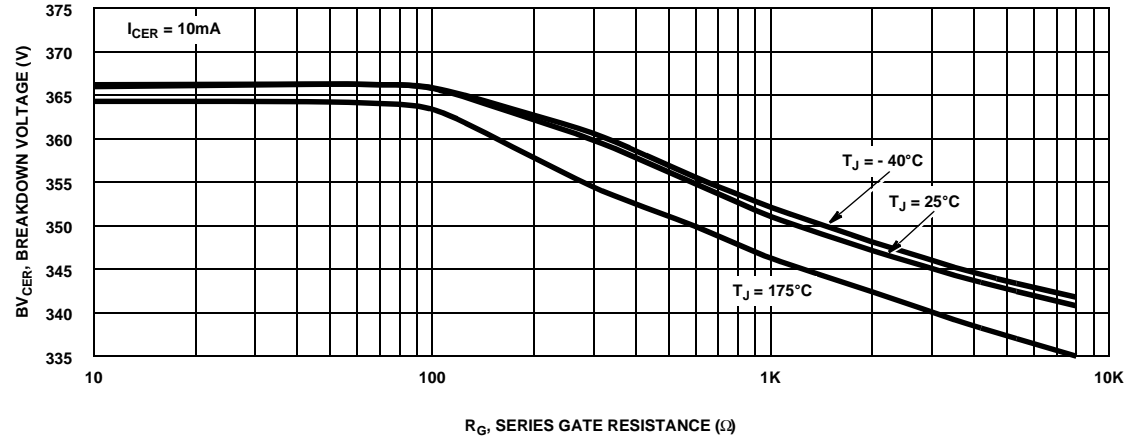


Figure 15. Breakdown Voltage vs Series Gate Resistance

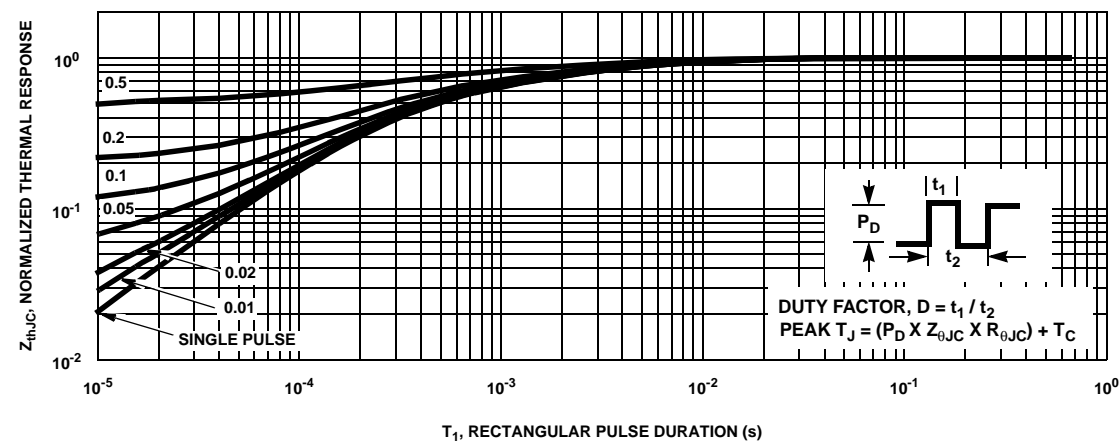


Figure 16. IGBT Normalized Transient Thermal Impedance, Junction to Case

Test Circuit and Waveforms

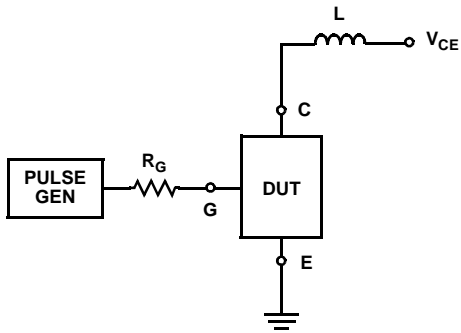


Figure 17. Inductive Switching Test Circuit

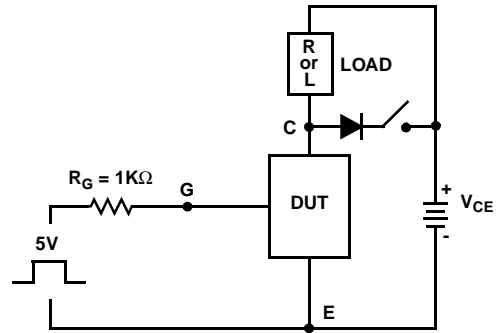


Figure 18.  $t_{ON}$  and  $t_{OFF}$  Switching Test Circuit

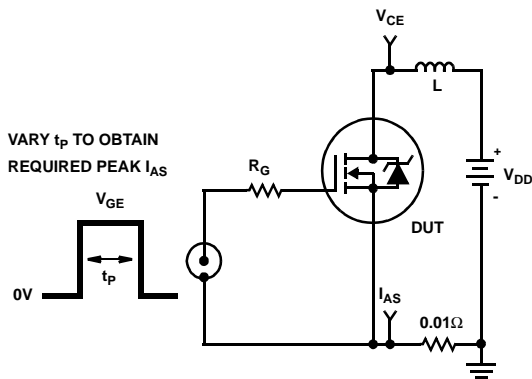


Figure 19. Unclamped Energy Test Circuit

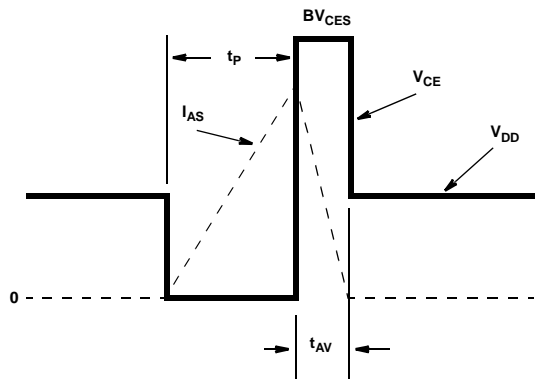


Figure 20. Unclamped Energy Waveforms

### SPICE Thermal Model

REV 24 April 2002

ISL9V3036D3S / ISL9V3036S3S / ISL9V3036P3

```

CTHERM1 th 6 2.1e -3
CTHERM2 6 5 1.4e -1
CTHERM3 5 4 7.3e -3
CTHERM4 4 3 2.1e -1
CTHERM5 3 2 1.1e -1
CTHERM6 2 tl 6.2e +6
    
```

```

R THERM1 th 6 1.2e -1
R THERM2 6 5 1.9e -1
R THERM3 5 4 2.2e -1
R THERM4 4 3 6.0e -2
R THERM5 3 2 5.8e -2
R THERM6 2 tl 1.6e -3
    
```

### SABER Thermal Model

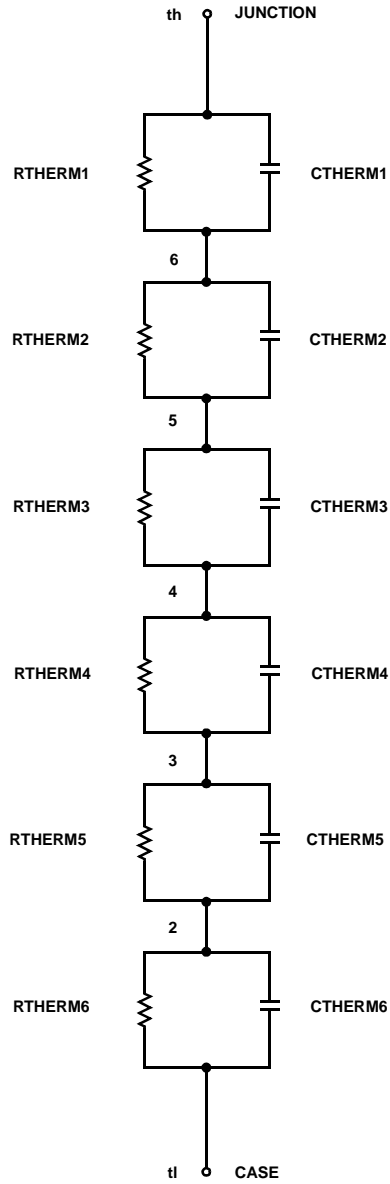
SABER thermal model  
 ISL9V3036D3S / ISL9V3036S3S / ISL9V3036P3  
 template thermal\_model th tl  
 thermal\_c th, tl

```

{
  ctherm.ctherm1 th 6 = 2.1e -3
  ctherm.ctherm2 6 5 = 1.4e -1
  ctherm.ctherm3 5 4 = 7.3e -3
  ctherm.ctherm4 4 3 = 2.2e -1
  ctherm.ctherm5 3 2 = 1.1e -1
  ctherm.ctherm6 2 tl = 6.2e +6
    
```

```

rtherm.rtherm1 th 6 = 1.2e -1
rtherm.rtherm2 6 5 = 1.9e -1
rtherm.rtherm3 5 4 = 2.2e -1
rtherm.rtherm4 4 3 = 6.0e -2
rtherm.rtherm5 3 2 = 5.8e -2
rtherm.rtherm6 2 tl = 1.6e -3
}
    
```



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Bottomless <sup>™</sup>	FAST <sub>r</sub> <sup>™</sup>	OPTOLOGIC <sup>®</sup>	SMART START <sup>™</sup>	UltraFET <sup>®</sup>
CoolFET <sup>™</sup>	FRFET <sup>™</sup>	OPTOPLANAR <sup>™</sup>	SPM <sup>™</sup>	VCX <sup>™</sup>
CROSSVOLT <sup>™</sup>	GlobalOptoisolator <sup>™</sup>	PACMAN <sup>™</sup>	STAR*POWER <sup>™</sup>	
DenseTrench <sup>™</sup>	GTO <sup>™</sup>	POP <sup>™</sup>	Stealth <sup>™</sup>	
DO <sub>M</sub> E <sup>™</sup>	HiSeC <sup>™</sup>	Power247 <sup>™</sup>	SuperSOT <sup>™</sup> -3	
EcoSPARK <sup>™</sup>	I <sup>2</sup> C <sup>™</sup>	PowerTrench <sup>®</sup>	SuperSOT <sup>™</sup> -6	
E <sup>2</sup> CMOS <sup>™</sup>	ISOPLANAR <sup>™</sup>	QFET <sup>™</sup>	SuperSOT <sup>™</sup> -8	
EnSigna <sup>™</sup>	LittleFET <sup>™</sup>	QS <sup>™</sup>	SyncFET <sup>™</sup>	
FACT <sup>™</sup>	MicroFET <sup>™</sup>	QT Optoelectronics <sup>™</sup>	TinyLogic <sup>™</sup>	
FACT Quiet Series <sup>™</sup>	MicroPak <sup>™</sup>	Quiet Series <sup>™</sup>	TruTranslation <sup>™</sup>	

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

## PRODUCT STATUS DEFINITIONS

### Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
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